

Grenzwerte ($T_A = 25\text{ °C}$)**Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{op}; T_{stg}$	- 40 ... + 100	°C
Sperrspannung Reverse voltage	V_R	3	V
Durchlassstrom Forward current	I_F (DC)	100	mA
Stoßstrom Surge current $t_p = 10\text{ }\mu\text{s}$, $D = 0$	I_{FSM}	2.2	A
Verlustleistung Power dissipation	P_{tot}	180	mW
Wärmewiderstand Sperrschicht - Umgebung, freie Beinchenlänge max. 10 mm Thermal resistance junction - ambient, lead length between package bottom and PCB max. 10 mm	R_{thJA}	375	K/W

Kennwerte ($T_A = 25\text{ °C}$)**Characteristics**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der Strahlung Wavelength of peak emission $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	λ_{peak}	950	nm
Spektrale Bandbreite bei 50% von I_{max} Spectral bandwidth at 50% of I_{max} $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	$\Delta\lambda$	40	nm
Abstrahlwinkel Half angle	φ	± 10	Grad deg.
Aktive Chipfläche Active chip area	A	0.09	mm ²
Abmessungen der aktiven Chipfläche Dimension of the active chip area	$L \times B$ $L \times W$	0.3×0.3	mm ²
Schaltzeiten, I_e von 10% auf 90% und von 90% auf 10% Switching times, I_e from 10% to 90% and from 90% to 10% $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$, $R_L = 50\text{ }\Omega$	t_r , t_f	10	ns
Kapazität Capacitance $V_R = 0\text{ V}$, $f = 1\text{ MHz}$	C_o	35	pF
Durchlassspannung Forward voltage $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$ $I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$	V_F V_F	1.5 (≤ 1.8) 3.2 (≤ 4.3)	V V
Sperrstrom Reverse current $V_R = 3\text{ V}$	I_R	0.01 (≤ 10)	μA
Gesamtstrahlungsfluss Total radiant flux $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	Φ_e	40	mW
Temperaturkoeffizient von I_e bzw. Φ_e Temperature coefficient of I_e or Φ_e $I_F = 100\text{ mA}$	TC_I	- 0.44	%/K

Kennwerte ($T_A = 25\text{ °C}$) (cont'd)**Characteristics**

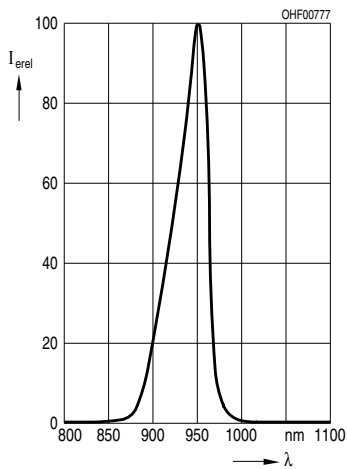
Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Temperaturkoeffizient von V_F Temperature coefficient of V_F $I_F = 100\text{ mA}$	TC_V	- 1.5	mV/K
Temperaturkoeffizient von λ Temperature coefficient of λ $I_F = 100\text{ mA}$	TC_λ	+ 0.2	nm/K

Strahlstärke I_e in Achsrichtunggemessen bei einem Raumwinkel von $\Omega = 0.01\text{ sr}$ **Radiant Intensity I_e in Axial Direction**measured at a solid angle of $\Omega = 0.01\text{ sr}$

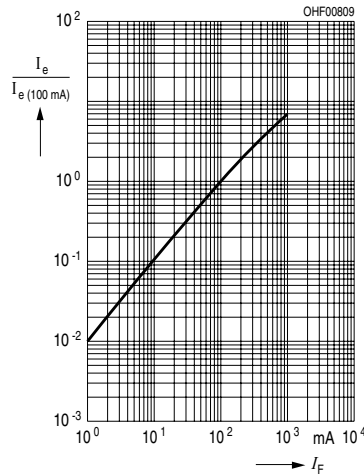
Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Strahlstärke Radiant intensity $I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	$I_{e\text{ min}}$ $I_{e\text{ typ}}$	25 85	mW/sr mW/sr
Strahlstärke Radiant intensity $I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$	$I_{e\text{ typ}}$	550	mW/sr

Relative Spectral Emission

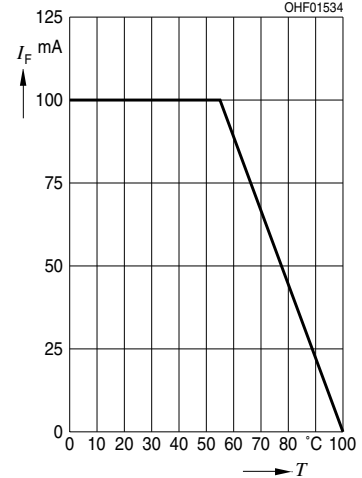
$$I_{\text{erel}} = f(\lambda)$$



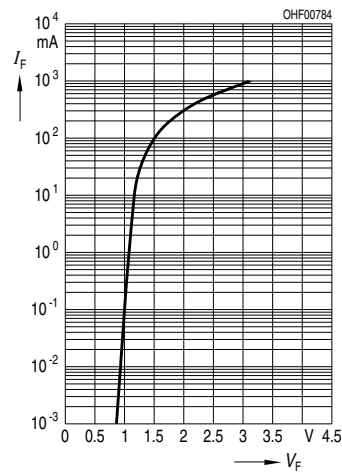
Radiant Intensity $I_e/I_e(100 \text{ mA}) = f(I_F)$ Single pulse, $t_p = 20 \mu\text{s}$



Max. Permissible Forward Current $I_F = f(T_A)$

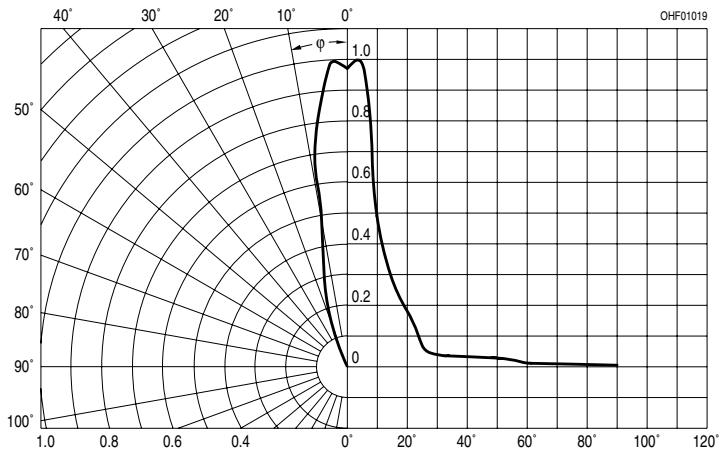


Forward Current $I_F = f(V_F)$ single pulse, $t_p = 20 \mu\text{s}$

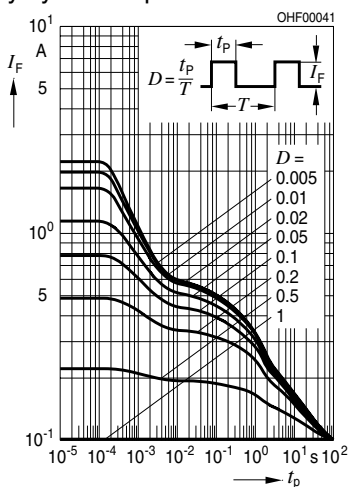


Radiation Characteristic

$$I_{\text{erel}} = f(\varphi)$$

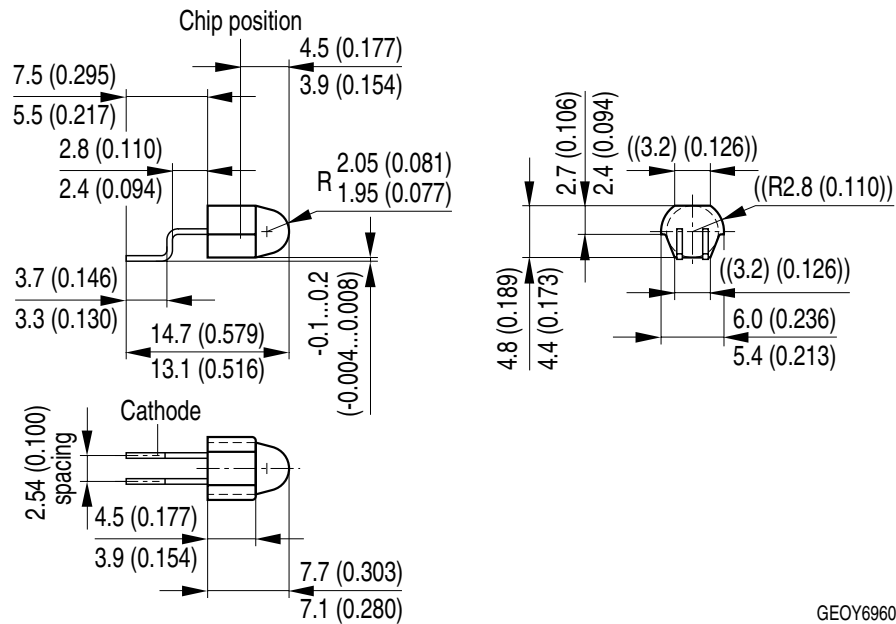


Permissible Pulse Handling Capability $I_F = f(\tau)$, $T_A = 25^\circ\text{C}$, duty cycle $D = \text{parameter}$

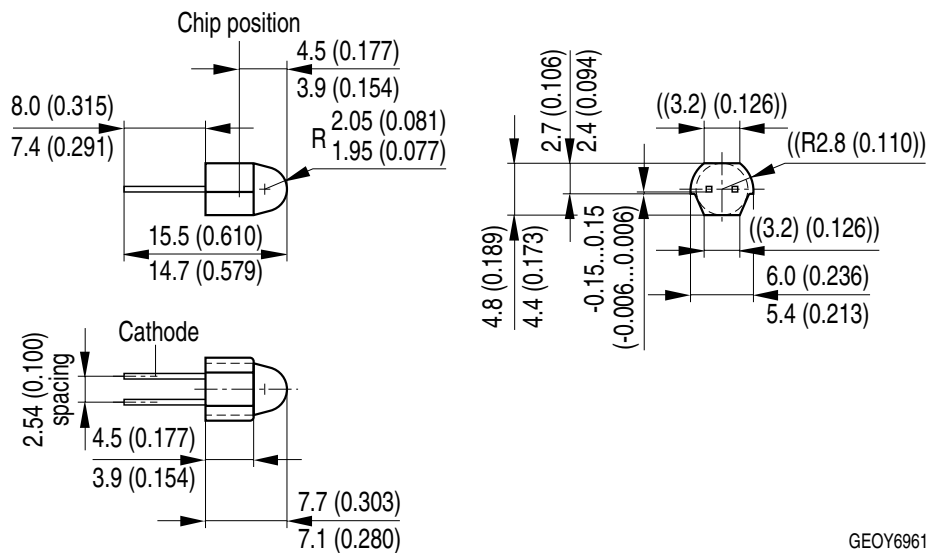


Maßzeichnungen Package Outlines

SFH 4500

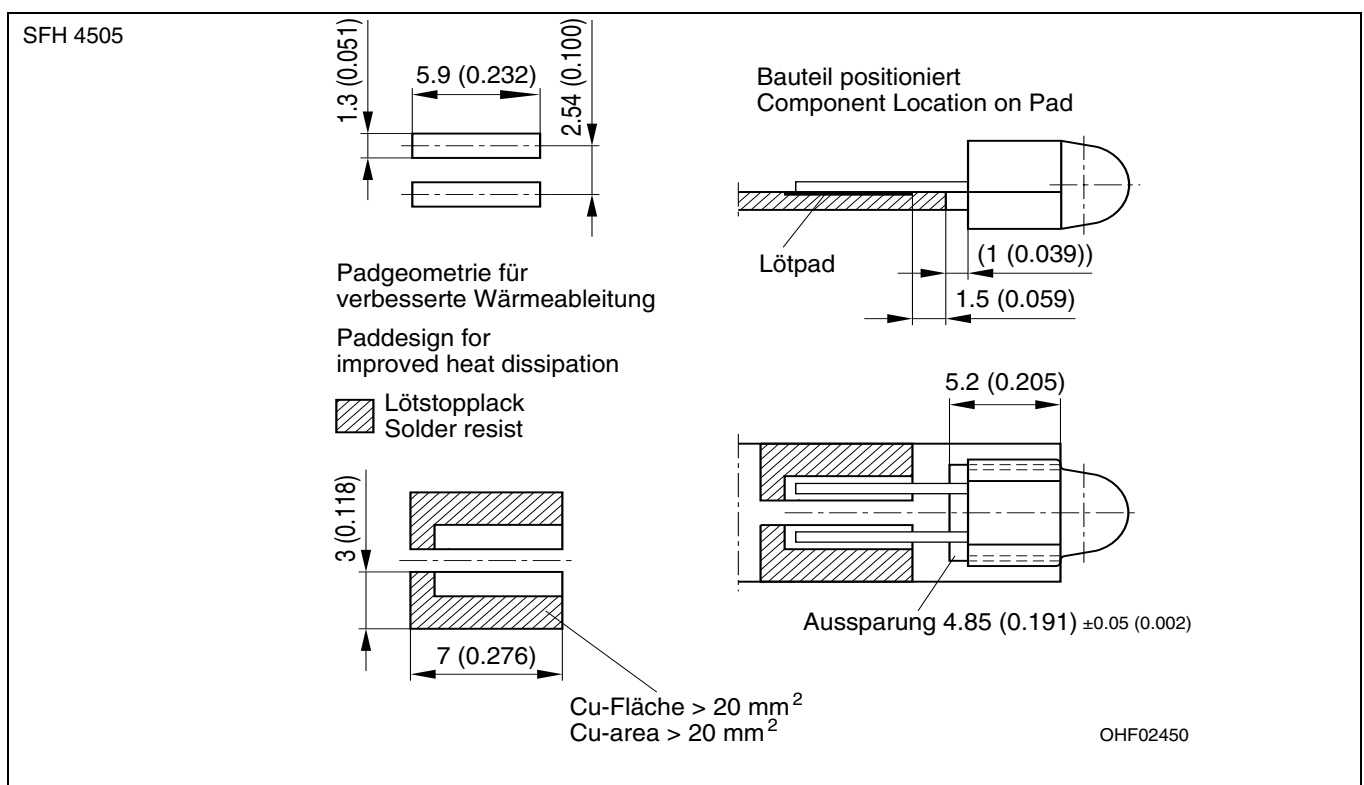
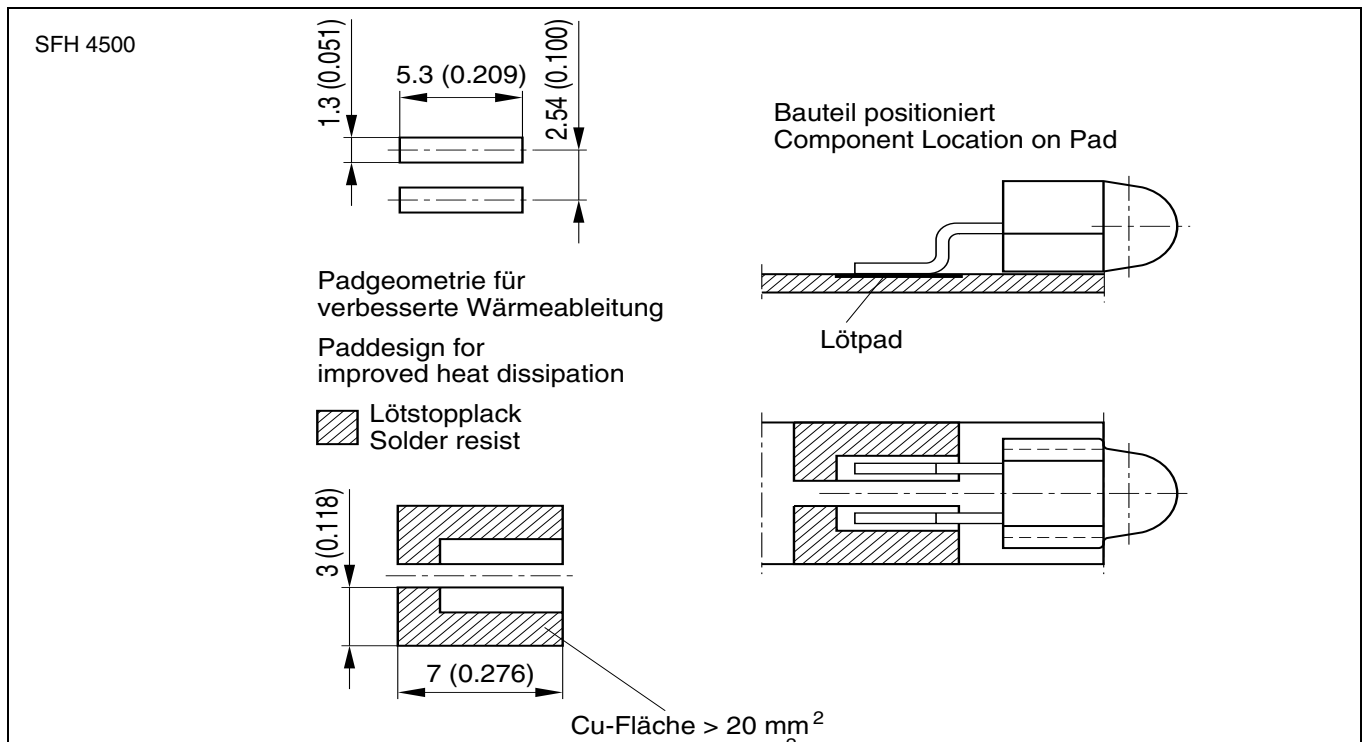


SFH 4505



Maße in mm (inch) / Dimensions in mm (inch).

Empfohlenes Lötpad Design Recommended Solder Pad



Maße in mm (inch) / Dimensions in mm (inch).

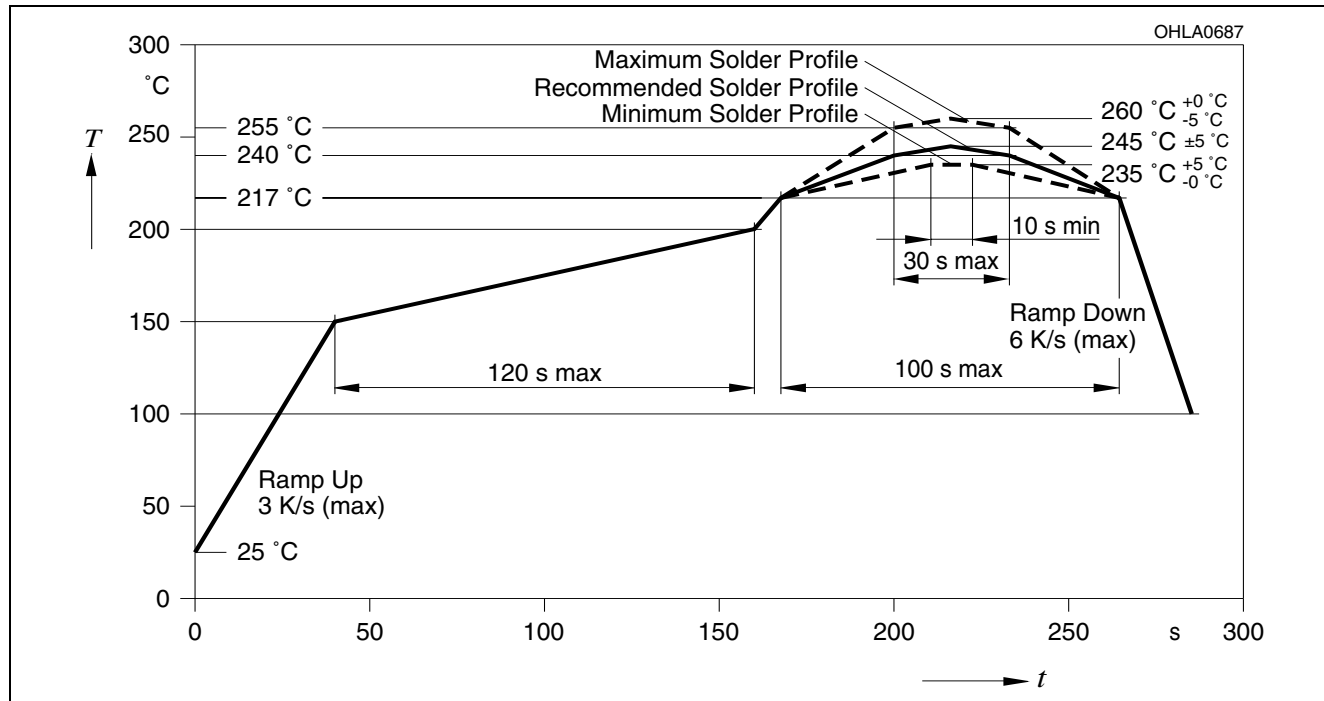
Lötbedingungen**Soldering Conditions****Reflow Lötprofil für bleifreies Löt****Reflow Soldering Profile for lead free soldering**

Vorbehandlung nach JEDEC Level 3

Preconditioning acc. to JEDEC Level 3

(nach J-STD-020C)

(acc. to J-STD-020C)



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